- Flatlink Interface Utilizes Low Power Differential Signalling(LVDS)
- Suitable for Notebook Application
- XGA Resolution
- Six Bit System Interface
- Support Mainstream Data and Gate Drivers
- Optional Configurable Pins

- Low Voltage CMOS 3.3 V Technology
- 65 MHz Phase-Lock Input
- 100-pin TQFP Package for Compact LCD Module
- Tolerates 4 kV HBM ESD for LVDS Pins and 2 kV HBM for Others
- Improved Jitter Tolerance

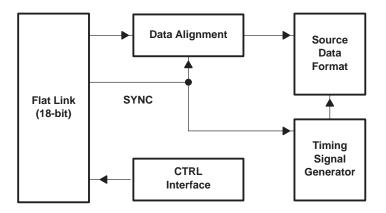
## description

The SN75LVDS88 (LVDS panel timing controller) integrates a Flatlink signal interface with a TFT LCD timing controller. It resides in the LCD panel and provides interface between the graphic controller and a TFT LCD panel.

The SN75LVDS88 accepts host data through 3 pairs of inputs (18-bits) making up the LVDS bus, which is a low-EMI high-throughput interface. SN75LVDS88 then reformats the received image data into a specific data format and synchronous timing suitable for driving LCD panel column and row drivers. This device supports XGA resolution.

The SN75LVDS88 is easily configured by several selection terminals and is equipped with default timing specifications to support mainstream gate and source drivers on the market.

## block diagram



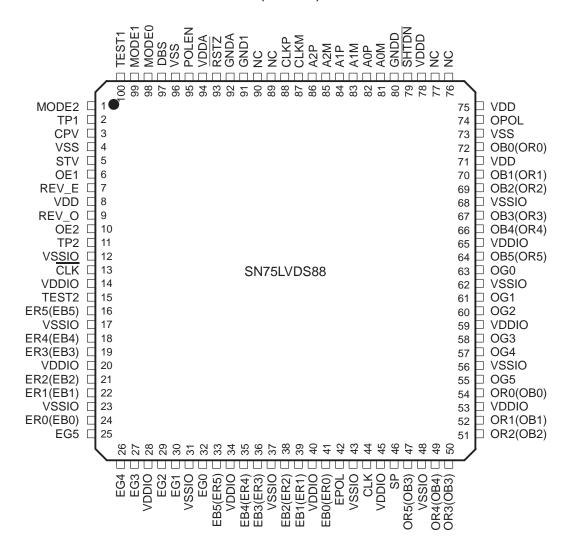


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## pin assignment

#### TQFP PACKAGE (TOP VIEW)





# **Terminal Functions**

TERMIN	TERMINAL		DECORIDETION				
NAME	NO.	1/0	DESCRIPTION				
A0M/A0P	81,82	ı	Flatlink 1 <sup>st</sup> data pair				
A1M/A1P	83, 84	Т	Flatlink 2 <sup>nd</sup> data pair				
A2M/A2P	85, 86	Т	Flatlink 3 <sup>rd</sup> data pair				
CLK	44	0	CD bus clock				
CLK	13	0	CD bus clock (180 degree out of phase)				
CLKM/CLKP	87, 88	Т	Flatlink clock pair				
CPV	3	0	Gate driver clock				
DBS	97	Τ	Data bus sequence				
EPOL	42	0	Even RGB data stream polarity indicator				
ER0ER5 (EB0)(EB5)	24,22,21 19,18,16	0	Even red (blue) data bus, controlled by DBS Pin, 0 = red, 1 = blue				
(ER0)(ER5) EB0EB5	41,39,38 36,35,33	0	Even blue (red) data bus, controlled by DBS Pin, 0 = blue, 1 = red				
GND1	91	Р	PLL ground for LVDS				
MODE0	98	Т	Default timing selection pin 0				
MODE1	99		Default timing selection pin 1				
MODE2	1	Ι	Default timing selection pin 2				
NC	76, 77, 89, 90	NC	NC terminals <sup>†</sup>				
OE1, OE2	6, 10	0	Gate driver output enable				
OG0OG5	63,61,60 58,57,55	0	Odd green data bus				
OPOL	74	0	Odd RGB data stream polarity indicator				
OR0OR5 (OB0)(OB5)	54,52,51 50,49,47	0	Odd red (blue) data bus, controlled by DBS Pin, 0 = red, 1 = blue				
(OR0)(OR5) OB0OB5	72,70,69 67,66,64	0	Odd blue (red) data bus, controlled by DBS Pin, 0 = blue, 1 = red				
POLEN	95	1	Output data polarity control enable /disable				
REV_E	7	0	CD line/dot inversion control signal				
REV_O	9	0	CD line/dot inversion control signal (180 degree of phase)				
RSTZ	93	ı	Reset, active low				
SHTDN	79	1	System shutdown control, active low				
SP	46	0	Data bus starting pulse				
STV	5	0	Gate driver starting pulse				
TEST1, TEST2	100, 15	ı	Test points <sup>†</sup>				
TP1, TP2	2, 11	0	CD output control signal				
VDDA	94	Р	PLL power for LVDS				
GNDA	92	Р	Analog ground for LVDS				
VDDD	78	Р	Digital power supply for LVDS				
GNDD	80	Р	Digital power ground for LVDS				
VDD	8,71,75	Р	Digital power				
VSS	4,73,96	Р	Digital ground				
VDDIO		Р	I/O power				
VSSIO		Р	I/O ground				

<sup>†</sup> Terminals must be connected to ground.



# SN75LVDS88 TFT LCD PANEL TIMING CONTROLLER WITH LVDS INTERFACE

SLLS344 – OCTOBER 1999

## options

## output control

PIN NAME	PIN NO.	INTERNAL C	ONNECTION	DESCRIPTION		
PIN NAME	FIN NO.	REQUIRED	SUGGESTED	DESCRIPTION		
MODE0 MODE1 MODE2	98 99 1	Pull-up Pull-up Pull-down		Default timing selection pin 0 Default timing selection pin 1 Default timing selection pin 2		
POLEN		Pull-down		0 = Output data reverse disable 1 = Output data reverse enable		
DBS	97	Pull-down		Data bus sequence 0 = normal (RGB) 1 = reverse (BGR)		

NOTE: DBS and POLEN functions must not be enabled together. The option pins must be connected to ground or VDD.

# absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> <sup>‡</sup>	0.5 V to 4 V
Voltage range at any terminal	0.5 V to V <sub>CC</sub> + 0.5 V
Continuous power dissipation	See Dissipation Rating Table
Storage temperature range, T <sub>Stg</sub>	
Electrostatic discharge: Class 3 A	4 kV
Class 2 B	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### **DISSIPATION RATING TABLE**

PACKAGE	T <sub>A</sub> ≤ 25°C	OPERATING FACTOR§	T <sub>A</sub> = 70°C
	POWER RATING	ABOVE T <sub>A</sub> = 25°C	POWER RATING
PFD	1.548 W	12 mW	1.012 W

<sup>§</sup> This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.



<sup>‡</sup> All voltage values are with respect to the GND terminals unless otherwise noted.

# recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		3	3.3	3.6	V
High-level input voltage, VIH	QUITDN				V
Low-level input voltage, V <sub>IL</sub>	SHTDN			0.8	V
Magnitude of differential input voltage, VID		0.1		0.6	V
Common–mode input voltage, V <sub>IC</sub>		$\frac{ V_{ID} }{2}$		$2.4 - \frac{ V_{ID} }{2}$	V

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
V <sub>IT+</sub>	Positive-going differential input voltage threshold				100	mV
V <sub>IT</sub> _	Negative-going differential input voltage threshold		-100			mV
		Disabled, all inputs to ground			360	μΑ
	CC Quiescent current (average) AnM a	Enabled, AnP at 1 V and AnM at 1.4 V, t <sub>C</sub> = 15.38 ns		80		
ICC		Enabled, C <sub>L</sub> = 8 pF, Grayscale pattern , t <sub>C</sub> = 15.38 ns		100		mA
		Enabled, C <sub>L</sub> = 8 pF, Worst-case pattern , t <sub>C</sub> = 15.38 ns		120		
lн	High-level input current (SHTDN)	VIH = VCC			±20	μΑ
IJL	Low-level input current (SHTDN)	V <sub>IL</sub> = 0 V			±20	μΑ
I <sub>IN</sub>	Input current (A inputs)	0 V ≤ V <sub>I</sub> ≤ 2.4 V			±20	μΑ
loz	High-impendance output current	VO = 0 V or VCC			±10	μΑ

<sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

## timing requirements

		MIN	TYP	MAX	UNIT
t <sub>C</sub> §	Input clock period	14.7		31.25	ns
t <sub>su</sub> /t <sub>h</sub>	Input set up or hold time	550			ps

<sup>§</sup> t<sub>C</sub> is defined as the mean duration of a minimum of 32,000 clock periods.

## output buffer rating

	MIN	TYP	MAX	UNIT
STV, SP		4		mA
CLK, CLK		12		mA
Data bus and remaining outputs		8		mA



<sup>&</sup>lt;sup>‡</sup> The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for the negative-going input voltage threshold only.

# switching characteristics

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tdr1	Input clock rising to output clock rising delay	C: = 100 pE	10		40	ns
<sup>t</sup> df1	Input clock rising to output clock falling delay	C <sub>L</sub> = 100 pF	10		40	ns
t <sub>su1</sub>	Data set up time, E/O RGB to CLK↑	C: 100 pF	10		20	ns
t <sub>h1</sub>	Data hold time, CLK↑ to E/O RGB	C <sub>L</sub> = 100 pF	10		20	ns
t(RSKM)	Receiver input skew margin, See Note 4	$t_C = 15.38 \text{ ns } (\pm 0.2\%),$  Input clock jitter   < 50 ps, See Note 5	550	700		ps
t <sub>en</sub>	Enable time, SHTDN to phase lock			1		ms
t <sub>dis</sub>	Disable time, SHTDN to off state			250		ns
t <sub>su2</sub>	SP setup time	C - 15 pE	10		20	ns
t <sub>h2</sub>	SP pulse hold time	$C_{SP} = 15 pF$	10		20	ns

- NOTES: 1.  $t_{RSKM}$  is the timing margin available to allocate to the transmitter and interconnection skews and clock jitter. The value of this parameter at clock periods other than 15.38 ns can be calculated from  $t_{RSKM} = \frac{t_c}{14}$ -300 ps.
  - 2. | Input clock jitter | is the magnitude of the change in the input clock period.

#### PARAMETER MEASUREMENT INFORMATION

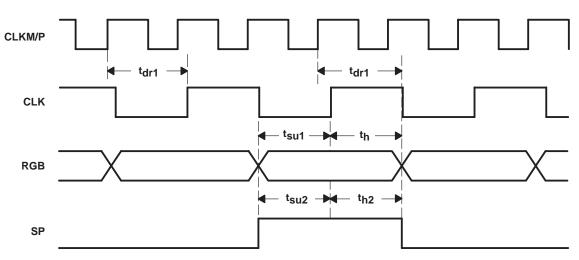


Figure 1. Output Setup and Hold Time

# REFERENCE TIMING DIAGRAM

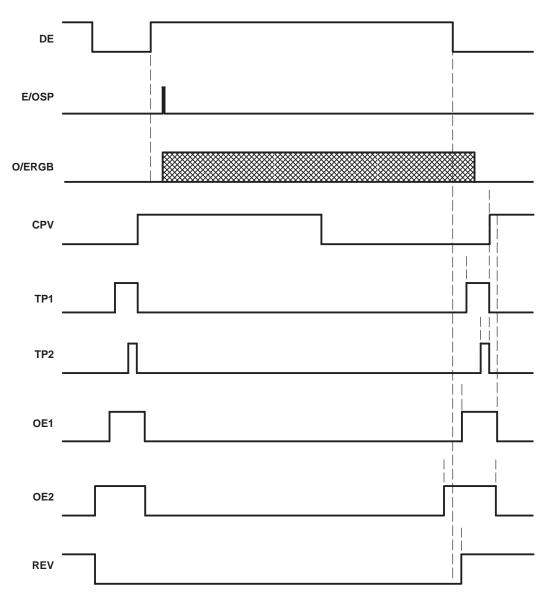


Figure 2. Typical Output Waveform

#### PARAMETER MEASUREMENT INFORMATION

#### functional description

#### **Flatlink**

The core of the Flatlink is TIs original 86A LVDS receiver which has three data channels for the 18-bit color plus one clock channel.

#### data alignment

The data alignment block supports dual bus dual port column driver configuration. When interfacing a 2-port column driver, the controller arranges pixels in odd and even order, then distributes them to odd and even buses and each connects to either of the driver ports. Under this setup, the controller outputs one clock, one or two data polarities (depends on driver), and one inverse ( support line inversion) signal to the drivers.

## output formatting

The output formatting provides several functions to reduce EMI, noise, and timing delay arrangement. These functions are controllable through some optional pins. See the registers and options section for reference.

Reverse Polarity Generation

When enable this function generates polarity indication signals. This occurs when the number of transitions in the output data bus exceeds 18-bits compared to the previous output under normal polarity. The polarity signal will be active and the output will be the opposite polarity to reduce transition

Line Inversion

When enabled, the REV\_O and REV\_E terminals will output the same line inversion control signals but in opposite polaritys.

#### timing control

Source Shifted Clock(SSC)

The master data clock could be arranged to have an intentional phase delay relative to the output data, which helps the system engineer tune the clock to latch the data correctly regardless of the characteristics presented by the PCB and the layout.

Horizontal Starting pulses

ESP and OSP terminals are used as the horizontal starting pulses outputs pins. Their output are one HCLK period ahead of the RGB data stream

Horizontal Clock

ECLK and OCLK terminals are responsible for the clock pulses, based on the XGA resolution when its frequency is at 32.5 MHz.

CD Data Latch Pulse

TP1 and TP2 provide the column driver input latch and output enable signals.

Gate Driver Clock

The CPV terminal output the clock pulses to the gate drivers as the horizontal sync timing in its CRT counter part.

Gate Driver Starting Pulse

The vertical starting pulse automatically generates at the start of every frame.

Gate Driver Output Enable

The OE1 and OE2 terminals provide the gate output enabale signals.



#### PARAMETER MEASUREMENT INFORMATION

## functional description (continued)

# vertical/horizontal reference generator

This block provides vertical and horizontal reference points for timing control. Vsync, Hsync, and ENAB signals along with the auto detection function determine when the video from the host is valid.

#### power-up procedure

Due to the uncertainty of registers and counters in the driver, SN75LVDS88 combines the input from both reset and Vsync to blank the output and simultaneously resets the content of drivers (see Figure 3).

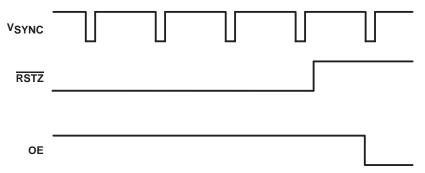
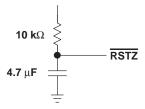


Figure 3. Reset Waveform

It is recommended that the following circuit be used to ensure the device is reset for more than 5 ms after power up.



## **APPLICATION INFORMATION**

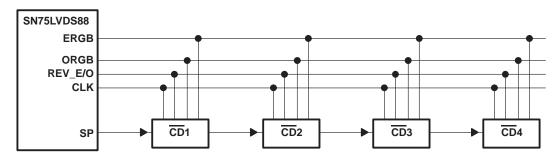


Figure 4. Application Block Diagram

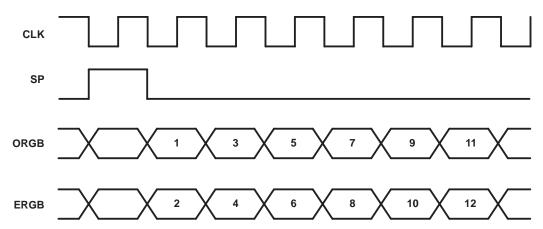


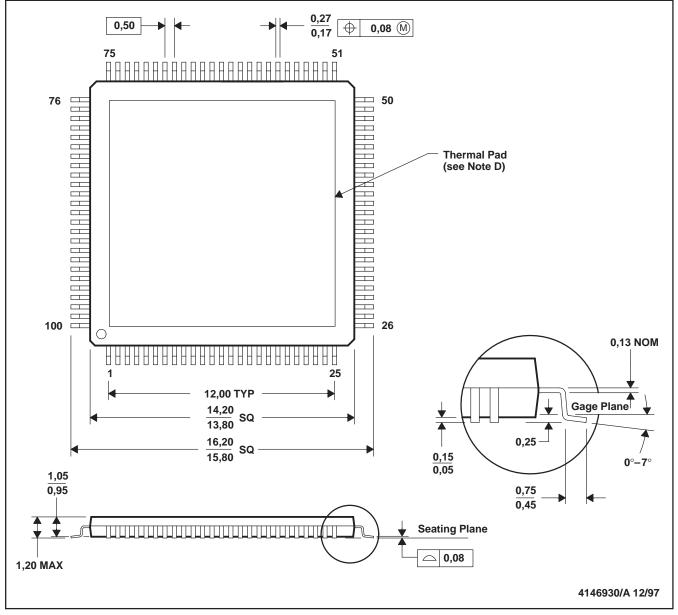
Figure 5. Data Output Format



# **MECHANICAL DATA**

## PFD (S-PQFP-G100)

# PowerPAD™ PLASTIC QUAD FLATPACK (DIE DOWN)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. The package thermal performance may be enhanced by attaching an external heatsink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MS-026

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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75LVDS88PFD	OBSOLETE	HTQFP	PFD	100	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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